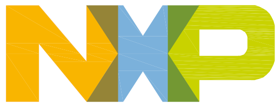

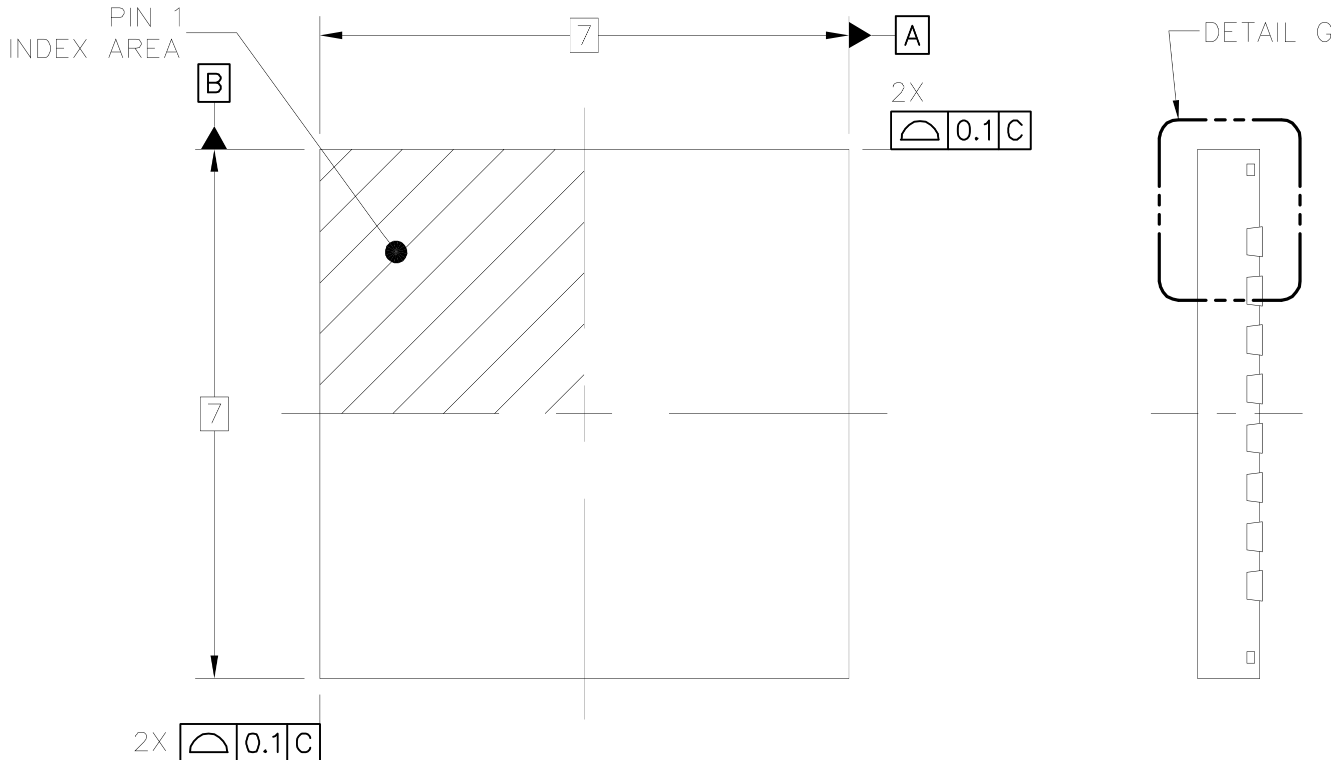

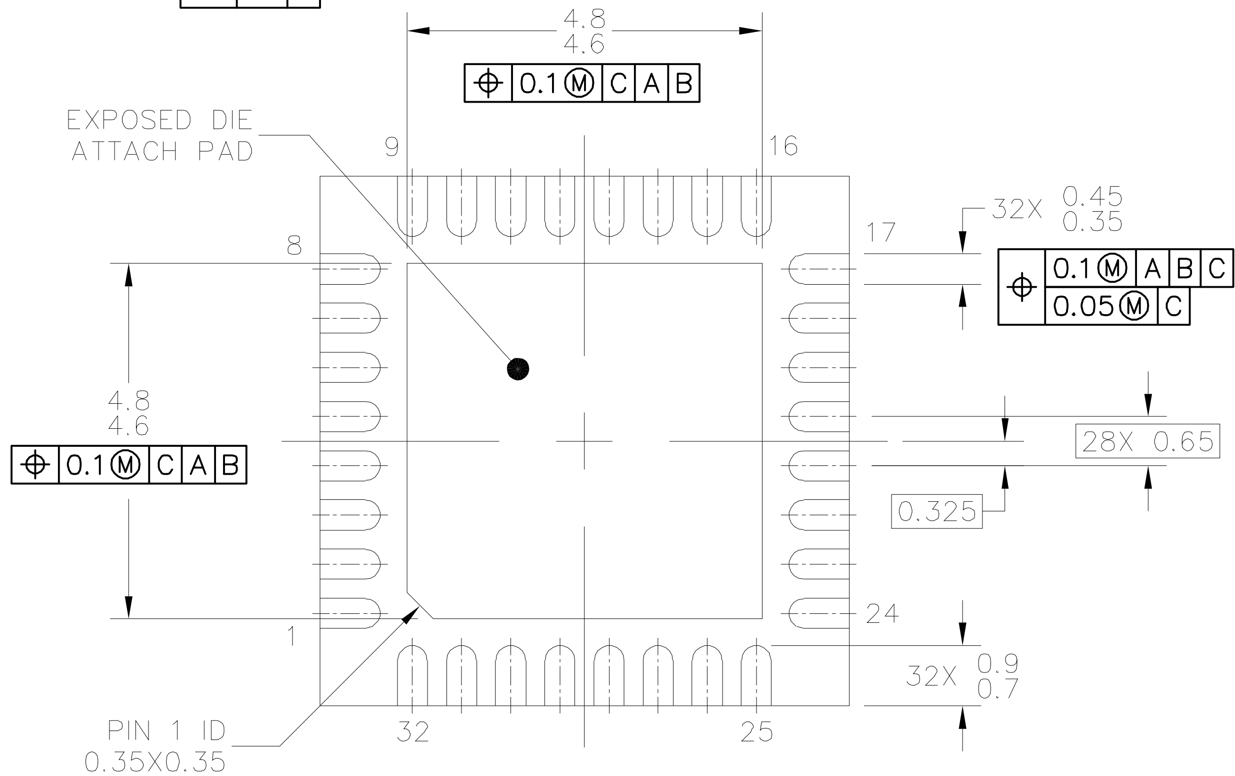

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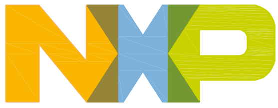
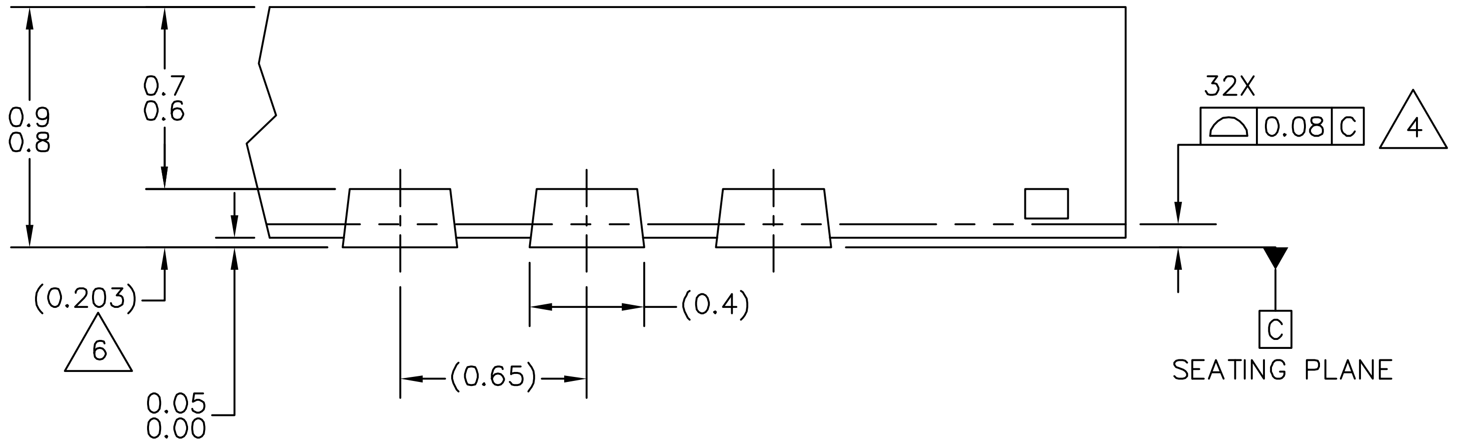
MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 0.85, 0.65 PITCH, 32 TERMINAL	DOCUMENT NO: 98ASA00756D	REV: B
	STANDARD: NON-JEDEC	
	SOT865-5	08 AUG 2016





DETAIL G
VIEW ROTATED 90°CW

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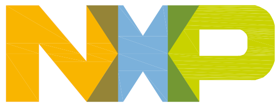
MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 0.85, 0.65 PITCH, 32 TERMINAL	DOCUMENT NO: 98ASA00756D REV: B
	STANDARD: NON-JEDEC
	SOT865-5 08 AUG 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.

3. THIS IS A NON−JEDEC REGISTERED PACKAGE.

4. COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH FLAG.

5. MIN METAL GAP SHOULD BE 0.2 MM.

6. MIN/MAX HEIGHT OF LEAD END SHOULD BE 0.15/0.25 MM.

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